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EUROPEAN PATENT APPLICATION

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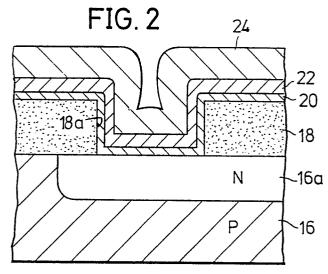
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54 Semiconductor device having a metallic layer.

(f) A semiconductor device comprises a silicon substrate (16), an insulating film (18) in which a contact hole (18a) is formed, a metallic layer (20) deposited on said silicon substrate through the contact hole, for forming an ohmic contact to the silicon substrate, a diffusion barrier layer (22) deposited on the metallic layer, for preventing reaction and interdiffusion between copper and silicon, and a metallization film (24) including at least copper deposited on the barrier layer.





EUROPEAN SEARCH REPORT

EP 87 30 8050

Category	Citation of document with of relevant p	indication, where appropriate,	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.4)
Υ		F JAPAN, vol. 9, no. 4th April 1985; &	1-7	H 01 L 23/48 H 01 L 23/52
Υ	IBM TECHNICAL DISC 29, no. 3, August 1395,1396, New Yorl barriers for CU" * The whole article	k, US; "Diffusion	1-7	
A	IBM TECHNICAL DISC 25, no. 2, July 198 New York, US; R.C.I "Process for forming stud"	_ANGE et al.:	1-4	
	EP-A-0 261 846 (FU * Figures; page 3,		1-7	TECHNICAL FIELDS SEARCHED (Int. Cl.4)
				H 01 L
	,			
	The present search report has b	een drawn up for all claims		
	Place of search	Date of completion of the searc	h	Examiner

EPO FORM 1503 03.82 (P0401)

CATEGORY OF CITED DOCUMENTS

- X: particularly relevant if taken alone
 Y: particularly relevant if combined with another document of the same category
 A: technological background
 O: non-written disclosure
 P: intermediate document

- T: theory or principle underlying the invention
 E: earlier patent document, but published on, or after the filing date
 D: document cited in the application
 L: document cited for other reasons

- &: member of the same patent family, corresponding document